

DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD OF WAFER PROCESSING WITH EDGE SEED LAYER REMOVAL; the specification of which was filed on **February 18, 2004** as Application Serial No. **10/782,697**.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim the benefit under Title 35, United States Codes § 119(e) of any United States provisional application listed below.

Application No.: 60/523,064

Filing Date: December 21, 2001

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below, and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S.A. Application

Application No.: 10/032,318

Filing Date: 12/21/01

Status: **Pending**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.



Full name of first inventor: **Bulent M. Basol**

Inventor's signature _____

Date _____

Residence: **Manhattan Beach, CA, USA**

Citizenship: **USA**

Mailing Address: **3001 Maple Ave., Manhattan Beach, CA 90266**

Full name of second inventor: **Homayoun Talieh**

Inventor's signature _____

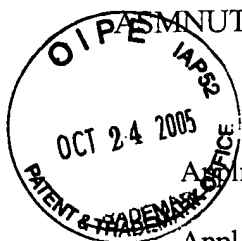
Date _____

Residence: **San Jose, CA, USA**

Citizenship: **USA**

Mailing Address: **2211 Bentley Ridge Dr. San Jose, CA 95138**

Send Correspondence To:
KNOBBE, MARTENS, OLSON & BEAR, LLP
Customer No. 20,995



ASMNUT.031CP1

PATENT

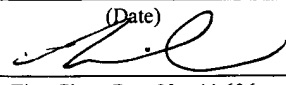
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Basol et al.
Appl. No. : 10/782,697
Filed : February 18, 2004
For : METHOD OF WAFER
PROCESSING WITH
EDGE SEED LAYER
REMOVAL
Examiner : Unknown
Art Unit : 2812

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 19, 2005

(Date)


Tina Chen, Reg. No. 44,606

NOTIFICATION OF LOSS OF ENTITLEMENT TO
SMALL ENTITY STATUS 37 C.F.R. § 1.28(b)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicant hereby notifies the Patent and Trademark Office that it is no longer entitled to status as a small entity and that the claim for small entity status is hereby withdrawn.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: October 19, 2005

By: 

Tina Chen

Registration No. 44,606

Attorney of Record

Customer No. 20,995

(415) 954-4114